INTEGRATED CIRCUITS

DATA SHEET



74LV74

Dual D-type flip-flop with set and reset; positive-edge trigger

Product specification
Supersedes data of 1996 Nov 07
IC24 Data Handbook

1998 Apr 20





Dual D-type flip-flop with set and reset; positive edge-trigger

74LV74

FEATURES

- Wide operating voltage: 1.0 to 5.5V
- Optimized for Low Voltage applications: 1.0 to 3.6V
- Accepts TTL input levels between V_{CC} = 2.7V and V_{CC} = 3.6V
- Typical V_{OLP} (output ground bounce) < 0.8V @ V_{CC} = 3.3V, $T_{amb} = 25^{\circ}C$
- Typical V_{OHV} (output V_{OH} undershoot) > 2V @ V_{CC} = 3.3V, $T_{amb} = 25^{\circ}C$
- Output capability: standard
- I_{CC} category: flip-flops

DESCRIPTION

The 74LV74 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT74.

The 74LV74 is a dual positive edge triggered, D-type flip-flop with individual data (D) inputs, clock (CP) inputs, set (\overline{S}_D) and (\overline{R}_D) inputs; also complementary Q and Q outputs.

The set and reset are asynchronous active LOW inputs and operate independently of the clock input. Information on the data input is transferred to the Q output on the LOW-to-HIGH transition of the clock pulse. The D inputs must be stable one set-up time prior to the LOW-to-HIGH clock transition, for predictable operation.

Schmitt-trigger action in the clock input makes the circuit highly tolerant to slower clock rise and fall times.

QUICK REFERENCE DATA

GND = 0V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay nCP to nQ, nQ nSD to nQ, nQ nRD to nQ, nQ	C _L = 15pF V _{CC} = 3.3V	11 14 14	ns
f _{max}	Maximum clock frequency	$C_L = 15pF$ $V_{CC} = 3.3V$	76	MHz
C _I	Input capacitance	·	3.5	pF
C _{PD}	Power dissipation capacitance per flip-flop	Notes 1 and 2	24	pF

NOTES:

- C_{PD} is used to determine the dynamic power dissipation (P_D in μW) P_D = C_{PD} × V_{CC}² x f_i + Σ (C_L × V_{CC}² x f_o) where: f_i = input frequency in MHz; C_L = output load capacitance in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V; Σ (C_L × V_{CC}² × f_o) = sum of the outputs.
 The condition is V_I = GND to V_{CC}

ORDERING INFORMATION

OTTO THE OTTO TO				
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
14-Pin Plastic DIL	-40°C to +125°C	74LV74 N	74LV74 N	SOT27-1
14-Pin Plastic SO	-40°C to +125°C	74LV74 D	74LV74 D	SOT108-1
14-Pin Plastic SSOP Type II	-40°C to +125°C	74LV74 DB	74LV74 DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to +125°C	74LV74 PW	74LV74PW DH	SOT402-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1, 13	$1\overline{R}_{D,} 2\overline{R}_{D}$	Asynchronous reset-direct input (active-LOW)
2, 12	1D, 2D	Data inputs
3, 11	1CP, 2CP	Clock input (LOW-to-HIGH), edge-triggered)
4, 10	1\$\overline{S}_{D,} 2\$\overline{S}_{D}\$	Asynchronous set-direct input (active-LOW)
5, 9	1Q, 2Q	True flip-flop outputs
6, 8	1Q _, 2Q	Complement flip-flop outputs
7	GND	Ground (0V)
14	V _{CC}	Positive supply voltage

FUNCTION TABLE

	INPU	OUTI	PUTS		
S _D	\overline{R}_{D}	СР	D	Q	Q
L	Н	Х	Х	Н	L
H	L	Х	X	L	Н
L	L	Х	X	Н	Н

	INPU	OUT	PUTS		
S _D	\overline{R}_{D}	СР	D	Q _{n+1}	Q _{n+1}
Н	Н	1	L	L	H
н	<u> Н</u>	1	Н	Н	L

= HIGH voltage level L LOW voltage level

don't care

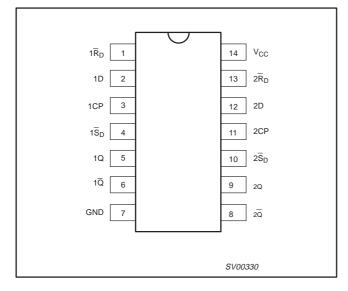
LOW-to-HIGH CP transition

 Q_{n+1} = state after the next LOW-to-HIGH CP transition

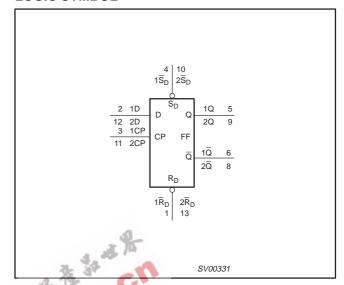
Dual D-type flip-flop with set and reset; positive edge-trigger

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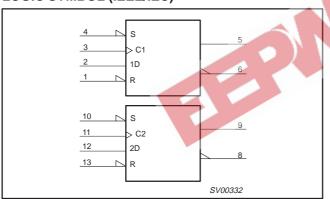
PIN CONFIGURATION



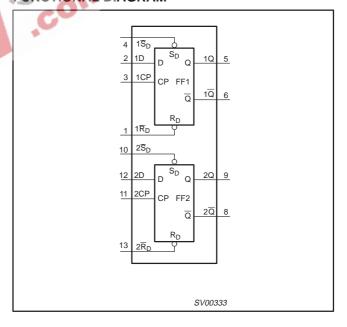
LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



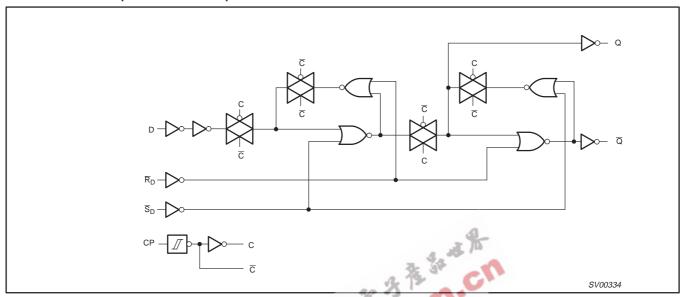
FUNCTIONAL DIAGRAM



Dual D-type flip-flop with set and reset; positive edge-trigger

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LOGIC DIAGRAM (ONE FLIP-FLOP)



RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
V _{CC}	DC supply voltage	See Note1	1.0	3.3	5.5	V
V _I	Input voltage		0	_	V _{CC}	V
Vo	Output voltage		0	-	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
t _r , t _f	Input rise and fall times except for Schmitt-trigger inputs	$V_{CC} = 1.0V \text{ to } 2.0V$ $V_{CC} = 2.0V \text{ to } 2.7V$ $V_{CC} = 2.7V \text{ to } 3.6V$ $V_{CC} = 3.6V \text{ to } 5.5V$		- - - -	500 200 100 50	ns/V

NOTE

1. The LV is guaranteed to function down to V_{CC} = 1.0V (input levels GND or V_{CC}); DC characteristics are guaranteed from V_{CC} = 1.2V to V_{CC} = 5.5V.

ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134)

Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
±I _{IK}	DC input diode current	$V_{I} < -0.5 \text{ or } V_{I} > V_{CC} + 0.5V$	20	mA
±lok	DC output diode current	$V_{O} < -0.5 \text{ or } V_{O} > V_{CC} + 0.5V$	50	mA
±l _O	DC output source or sink current – standard outputs	$-0.5V < V_O < V_{CC} + 0.5V$	25	mA
±I _{GND} , ±I _{CC}	DC V _{CC} or GND current for types with –standard outputs		50	mA
T _{stg}	Storage temperature range		-65 to +150	°C
	Power dissipation per package	for temperature range: -40 to +125°C		
P _{tot}	-plastic DIL	above +70°C derate linearly with 12mW/K	750	mW
' tot	-plastic mini-pack (SO)	above +70°C derate linearly with 8 mW/K	500	11100
	-plastic shrink mini-pack (SSOP and TSSOP)	above +60°C derate linearly with 5.5 mW/K	400	

NOTES:

^{1.} Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	-40)°C to +8	5°C	-40°C to	+125°C	Tואט
			MIN	TYP ¹	MAX	MIN	MAX	1
		V _{CC} = 1.2V	0.9			0.9		
V_{IH}	HIGH level Input	V _{CC} = 2.0V	1.4			1.4]
VIН	voltage	V _{CC} = 2.7 to 3.6V	2.0			2.0]
		V _{CC} = 4.5 to 5.5V	0.7*V _{CC}			0.7*V _{CC}		
		V _{CC} = 1.2V			0.3		0.3	
V_{IL}	LOW level Input	V _{CC} = 2.0V			0.6		0.6] _/
V IL	voltage	V _{CC} = 2.7 to 3.6V			0.8		0.8] `
		V _{CC} = 4.5 to 5.5			0.3*V _{CC}		0.3*V _{CC}	
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$		1.2				
	LUGULIII	$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	1.8	2.0		1.8]
V_{OH}	HIGH level output voltage; all outputs	$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $-I_O = 100\mu A$	2.5	2.7	5	2.5		V
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	2.8	3.0	-	2.8]
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	4.3	4.5	77.	4.3]
V _{OH}	HIGH level output voltage;	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 6\text{mA}$	2.40	2.82		2.20		V
VOH	STANDARD outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 12\text{mA}$	3.60	4.20		3.50		
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu\text{A}$		0				
	LOW level output	$V_{CC} = 2.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 100\mu A$		0	0.2		0.2	
V_{OL}	voltage; all outputs	$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 100\mu A$		0	0.2		0.2	٧
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2]
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	
V _{OL}	LOW level output voltage;	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 6\text{mA}$		0.25	0.40		0.50	
*OL	STANDARD outputs	$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 12\text{mA}$		0.35	0.55		0.65	ľ
II	Input leakage current	$V_{CC} = 5.5V$; $V_I = V_{CC}$ or GND			1.0		1.0	μА
I _{CC}	Quiescent supply current; flip-flops	$V_{CC} = 5.5V; V_I = V_{CC} \text{ or GND}; I_O = 0$			20.0		80	μА
Δl _{CC}	Additional quiescent supply current per input	$V_{CC} = 2.7V$ to 3.6V; $V_I = V_{CC} - 0.6V$			500		850	μА

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NOTE:
1. All typical values are measured at T_{amb} = 25°C.

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AC CHARACTERISTICS

GND = 0V; t_r = $t_f \le$ 2.5ns; C_L = 50pF; R_L = 1K Ω

SYMBOL	PARAMETER	WAVEFORM	CONDITION		LIMITS 40 to +85 °			IITS +125 °C	UNIT	
			V _{CC} (V)	MIN	TYP ¹	MAX	MIN	MAX		
			1.2	-	70	-	-	-		
			2.0	-	24	44	-	56		
t _{PHL} /t _{PLH}	Propagation delay nCP to nQ, nQ	Figures, 1, 3	2.7	-	18	28	-	41	ns	
	nce to fig, fig		3.0 to 3.6	-	13 ²	26	-	33		
			4.5 to 5.5	-	9.5 ³	17	-	23		
			1.2	-	90	_	-	-		
			2.0	-	31	46	-	58		
t _{PHL/} t _{PLH}	Propagation delay nS _D to nQ, nQ	Figures 2, 3	2.7	_	23	34	-	43	ns	
	I IISD to IIQ, IIQ		3.0 to 3.6	-	17 ²	27	-	34		
			4.5 to 5.5	-	12 ³	19	-	24		
			1.2	-	90	_	-	-		
			2.0	3.1	31	46	-	58		
t _{PHL} /t _{PLH}	Propagation delay nR _D to nQ, nQ	Figures 2, 3	2.7	E -30	23	34	-	43	ns	
	TIND to fig, fig		3.0 to 3.6	-	172	27	-	34		
			4.5 to 5.5	-(-) I	12 ³	19	-	24		
			2.0	34	10	_	41	-		
	Clock pulse width	_ , ,	2.7	25	8	_	30	-	ns	
t₩	HIGH to LOW	Figure 1	3.0 to 3.6	20	7 ²	_	24	-		
			4.5 to 5.5	15	6 ³	_	18	-		
	Set or reset pulse		2.0	34	10	_	41	-		
		Fr 0	27 25 8		8	-	30	-		
t₩	width LOW	Figure 2	3.0 to 3.6	20	7 ²	_	24	-	ns	
			4.5 to 5.5	15	6 ³	_	18	-		
			1.2	_	5	-	-	-		
			2.0	14	2	_	15	-	┨	
t _{rem}	Removal time set or reset	Figure 2	2.7	10	1	_	11	-	ns	
-	Set of feset		3.0 to 3.6	8	1 ²	_	9	-		
			4.5 to 5.5	6	1 ³	_	7	-		
			1.2	-	10	_	-	-		
			2.0	22	4	_	26	-		
t _{su}	Set-up time nD to nCP	Figure 1	2.7	12	3	_	15	-	ns	
	IID to fice		3.0 to 3.6	8	2 ²	_	10	-		
			4.5 to 5.5	6	1 ²	_	8	-		
			1.2	_	-10	_	-	-		
			2.0	3	-2	-	3	-		
t _h	Hold time nD to nCP	Figure 1	2.7	3	-2	-	3	-	ns	
••			3.0 to 3.6	3	-2 ²	-	3	-		
			4.5 to 5.5	3	-2 ³	-	3	-	1	
			2.0	14	40	-	12	-		
	Maximum clock		2.7	50	90	-	40	-		
f_{max}	pulse frequency	Figure 1	3.0 to 3.6	60	100 ²	-	48	-	MHz	
	l		4.5 to 5.5	70	110 ³	_	56	_		

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NOTE:

1. Unless otherwise stated, all typical values are at T_{amb} = 25°C.

^{2.} Typical value measured at $V_{CC} = 3.3V$.

^{3.} Typical value measured at $V_{CC} = 5.0V$.

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AC WAVEFORMS

 V_M = 1.5V at $V_{CC} \ge 2.7V \le 3.6V$ V_M = 0.5 * V_{CC} at $V_{CC} < 2.7V$ and $\ge 4.5V$

 $V_{\mbox{\scriptsize OL}}$ and $V_{\mbox{\scriptsize OH}}$ are the typical output voltage drop that occur with the output load.

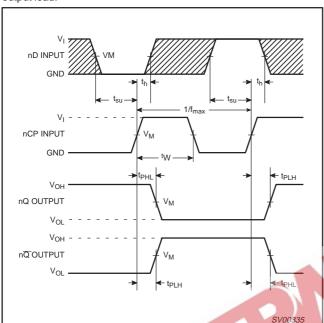


Figure 1.The clock (nCP) to output (nQ, nQ) propagation delays, the clock pulse width, the nD to nCP setup times, the nCP to nD hold times, the output transition times and the maximum clock pulse frequency

NOTE:

The shaded areas indicate when the input is permitted to change for predictable output performance.

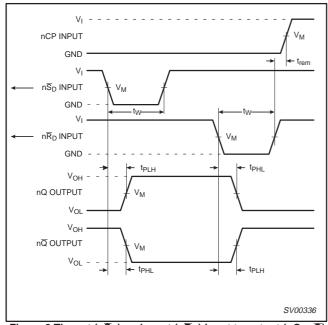


Figure 2.The set $(n\overline{S}_D)$ and reset $(n\overline{R}_D)$ input to output $(nQ, n\overline{Q})$ propagation delays, the set and reset pulse widths and the $n\overline{R}_D$ to nCP removal time

TEST CIRCUIT

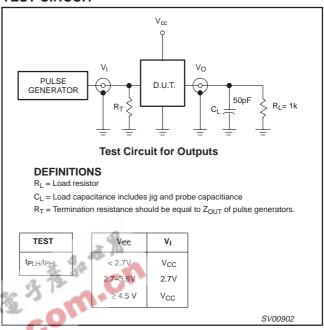


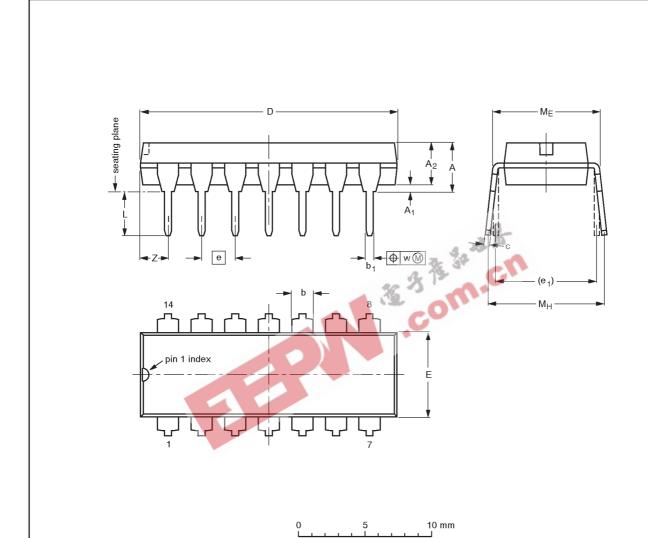
Figure 3. Load circuitry for switching times

Dual D-type flip-flop with set and reset; positive edge-trigger

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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

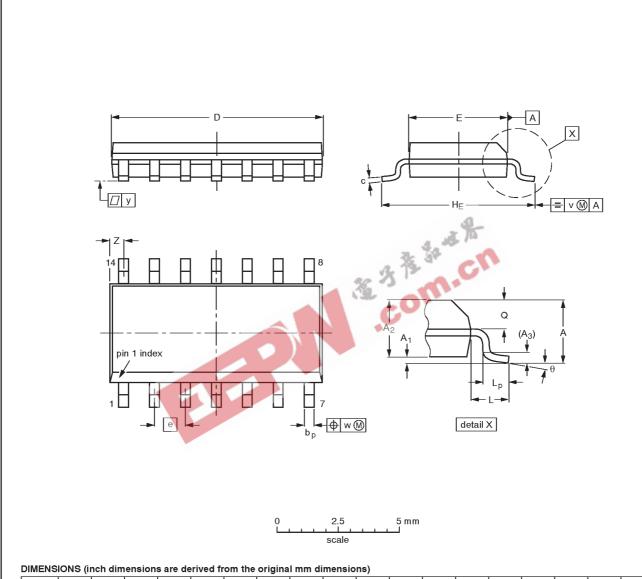
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT27-1	050G04	MO-001AA			92-11-17 95-03-11

Dual D-type flip-flop with set and reset; positive edge-trigger

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SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DINILIAO																		
UNIT	A max.	Α1	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069			0.01	ı	0.0098 0.0075	0.35 0.34	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

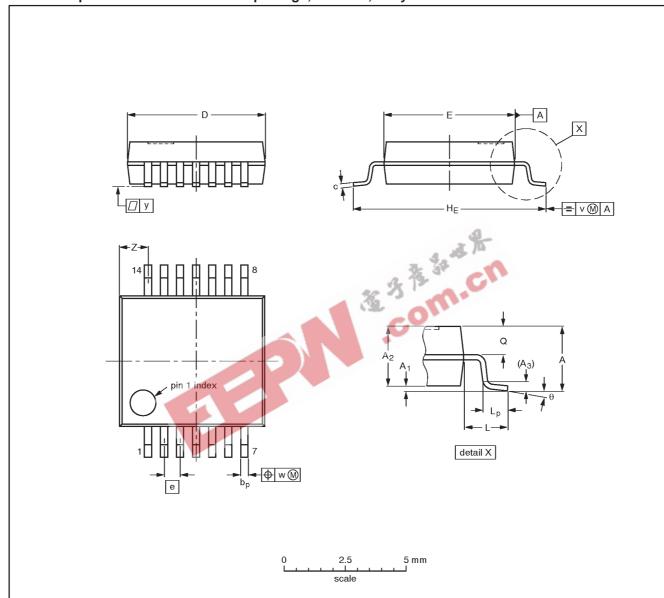
OUTLINE		EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		ISSUE DATE	
SOT108-1	076E06\$	MS-012AB				91 08-13 95-01-23

Dual D-type flip-flop with set and reset; positive edge-trigger

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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



DIMENSIONS (mm are the original dimensions)

						-,												
UNIT	A max.	Α ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

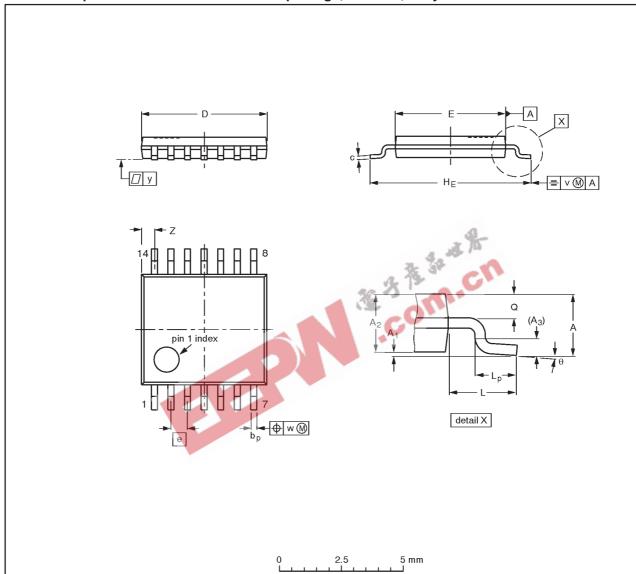
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT337-1		MO-150AB				-95-02-04 96-01-18

Dual D-type flip-flop with set and reset; positive edge-trigger

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TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	А3	рb	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	٧	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION		
SOT402-1		MO-153			-94-07-12 95-04-04	

Dual D-type flip-flop with set and reset; positive edge-trigger

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Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.

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